

**In The Claims:**

1. (original) A bump layout on a driver integrated chip (IC) having an active region, wherein the bumps are positioned in an array format over the active region.
2. (original) The bump layout of claim 1, wherein the active region further includes a plurality of circuit blocks.
3. (original) The bump layout of claim 2, wherein the circuit blocks are laid down in the bump space between neighboring bumps.
4. (original) The bump layout of claim 1, wherein the bumps are positioned in vertically aligned rows.
5. (original) The bump layout of claim 1, wherein the bumps are positioned in alternatively staggered rows.
6. (original) The bump layout of claim 1, wherein the bumps are positioned in vertically aligned rows on part of the active region and in alternatively staggered rows on another part of the active region.

Claims 7- 13 (Cancelled)

14. (new) The bump layout of claim 1, wherein the bumps are positioned in vertically aligned rows on part of the active region.

**Response to 35 U.S.C. 121**

The Examiner issued a restriction requirement. According to the Office Action, there are at least four patentably distinct species in the claimed invention and a restriction to one of these species in claims is required under 35 U.S.C. 121.

Applicants elect Species I related to a bump layout on a driver integrated circuit (IC) having an active region as shown in Fig. 3, specified in claims 1-4 and newly added claim 14, with traverse according to the following remarks. Applicants also reserve the right to pursue the subject matter of the non-elected claims in a divisional application if Applicants so choose.

As defined in MPEP §806.04(e), the term “species” is defined as the “specifically different embodiments” of an invention disclosed in the patent application. However, the elected species related to Fig.3 and the other asserted species related to Fig.4 are not specifically different embodiments of the invention. The bump layouts as defined in Fig. 3 or Fig. 4 are both related the bumps positioned in an array format over the active region of the driver IC, so that pressure is evenly distributed during chip-on-glass (COG) manufacturing. Claim 1 is the generic claim encompassing the two species as defined in Fig. 3 and Fig. 4. If the generic claim is held allowable, an applicant may include additional claims directed to a reasonable number of species so long as these additional claims “are written in dependent form or otherwise include all the limitations of the generic claim.” Therefore, Applicants respectfully request the restriction requirement of the species related to Fig.4 be withdrawn. The claims species 5 and 6 related to the species defined in Fig.4 should be examined in the application.

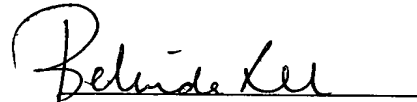
### CONCLUSION

In view of the foregoing, Applicants respectfully request reconsideration and the restriction requirement of Fig.4 specified in claims 5-6 be traversed. In the event a telephone conversation would expedite the prosecution of this application, the Examiner is encouraged to contact the undersigned attorney to discuss the application.

Respectfully submitted,

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